



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **WP1705-01(R1)** DATE: July 26, 2017

Product Affected: P9221-RAHGI,
P9221-RAHG18

Date Effective: August 31, 2017

MEANS OF DISTINGUISHING CHANGED DEVICES:

- Product Mark
- Back Mark
- Date Code
- Other

Traceable by Assembly lot#

Contact: IDT PCN DESK

Attachment: Yes No

E-mail: pcndesk@idt.com

Samples: Please contact your local sales representative for sample request.

DESCRIPTION AND PURPOSE OF CHANGE:

- Die Technology
- Wafer Fabrication Process
- Assembly Process
- Equipment
- Material
- Testing
- Manufacturing Site
- Data Sheet
- Other - Firmware change

Revision 1: This revised notice is to add additional firmware updates as follows:
 1. Improve the Extended Power Profile (EPP) Foreign Object Detection (FOD) to support a broader range of customer applications.
 2. Enable Ts (H4) pin for End of Charge (EOC), which will allow any WPC transmitter to be placed in a low state mode (where power will not be transferred) when I2C is not available. This pin definition will be outlined in an updated datasheet.

The PCN effective date remains unchanged.

RELIABILITY/QUALIFICATION SUMMARY:

There is no change in die technology/process/datasheet.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____

Approval for shipments prior to effective date.

Name/Date: _____

E-Mail Address: _____

Title: _____

Phone # /Fax #: _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____

DATE: _____